

U.S. Express Mail Label No.: EH920330411US

PATENT (U.S.A.)
ATTORNEY'S DOCKET NO.: UMC-96-279

**DECLARATION
and POWER OF ATTORNEY**

X ORIGINAL
CONTINUATION
DIVISIONAL

As the below named inventors, we declare that the information given herein is true, that we believe that we are the original inventors of the invention entitled:

High Density Plasma Chemical Vapor Deposition Process

Which is described and claimed in:

- x the attached specification or
the specification in application Serial No. filed
as amended on _____

(for declaration not accompanying application) (if applicable)

and for which a patent is sought, and that our residences, post office addresses and citizenship are as stated below next to our names.

We acknowledge our duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations § 1.56(a).

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We hereby claim foreign priority benefits under Title 35, United States, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

| COUNTRY | APPLICATION NUMBER | DATE OF FILING Month Day Year | PRIORITY CLAIMED UNDER 35 U.S.C. 119 |
|---------|--------------------|----------------------------------|--|
| | | | <input type="checkbox"/> YES |
| | | | <input type="checkbox"/> YES |

We hereby claim priority benefits under Title 35, United States, § 119(e) of any provisional application(s) listed below:

| COUNTRY | APPLICATION NUMBER | DATE OF FILING Month Day Year | PRIORITY CLAIMED UNDER 35 U.S.C. 119 |
|---------|--------------------|----------------------------------|--|
| | 60/041,790 | April 2, 1997 | <input checked="" type="checkbox"/> YES |
| | | | <input type="checkbox"/> YES |

We hereby claim the benefit under Title 35, United States Code § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

| (Application Serial No.) | (Filing Date) | (Status) |
|--------------------------|---------------|----------|
|--------------------------|---------------|----------|

POWER OF ATTORNEY: As a named Inventor, I hereby appoint the following attorney(s) and/or Agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

WILLIAM H. WRIGHT, Reg. No. 36,312, J. NICHOLAS GROSS, Reg. No. 34,175 and ALAN S. RAYNES, Reg. No. 39,809

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(310) 556-7983

DECLARATION and POWER OF ATTORNEY
PAGE 2.

| | | | | | | |
|---|--|--------------------|--------------------------|-------------|------------------------------------|------------------------------------|
| 1 | Name of Inventor | LAST NAME Liu | FIRST NAME Chih-Chien | MIDDLE NAME | Residence: CITY Taipei | STATE or COUNTRY Taiwan, R.O.C. |
| | Post Office Address c/o United Microelectronics Corporation, No. 13 Innovation First Road, Science Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C. | | | | CITIZENSHIP: <u>Taiwan, R.O.C.</u> | |
| 2 | Name of Inventor | LAST NAME Tseng | FIRST NAME Ta-Shan | MIDDLE NAME | Residence: CITY Taipei | STATE or COUNTRY Taiwan, R.O.C. |
| | Post Office Address c/o United Microelectronics Corporation, No. 13 Innovation First Road, Science Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C. | | | | CITIZENSHIP: <u>Taiwan R.O.C.</u> | |
| 3 | Name of Inventor | LAST NAME Shieh | FIRST NAME W.B. | MIDDLE NAME | Residence: CITY Hsin-Chu City | STATE or COUNTRY Taiwan, R.O.C. |
| | Post Office Address c/o United Microelectronics Corporation, No. 13 Innovation First Road, Science Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C. | | | | CITIZENSHIP: <u>Taiwan R.O.C.</u> | |
| 4 | Name of Inventor | LAST NAME Wu | FIRST NAME J.Y. | MIDDLE NAME | Residence: CITY Hsin-Chu City | STATE or COUNTRY Taiwan, R.O.C. |
| | Post Office Address c/o United Microelectronics Corporation, No. 13 Innovation First Road, Science Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C. | | | | CITIZENSHIP: <u>R.O.C.</u> | |
| 5 | Name of Inventor | LAST NAME Lur | FIRST NAME Water | MIDDLE NAME | Residence: CITY Taipei | STATE or COUNTRY Taiwan, R.O.C. |
| | Post Office Address c/o United Microelectronics Corporation, No. 13 Innovation First Road, Science Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C. | | | | CITIZENSHIP: <u>Taiwan, R.O.C.</u> | |
| 6 | Name of Inventor | LAST NAME Sun | FIRST NAME Shih-Wei | MIDDLE NAME | Residence: CITY Taipei | STATE or COUNTRY Taiwan, R.O.C. |
| | Post Office Address c/o United Microelectronics Corporation, No. 13 Innovation First Road, Science Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C. | | | | CITIZENSHIP: <u>R.O.C.</u> | |

We further declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

| | |
|---|---|
| SIGNATURE OF INVENTOR 1 <u>Liu, Chih-Chien</u> | SIGNATURE OF INVENTOR 2 <u>Ta-Shan Tseng</u> |
| DATE <u>6/24/97</u> | DATE <u>6/24/97</u> |
| SIGNATURE OF INVENTOR 3 <u>W.B. Shieh</u> | SIGNATURE OF INVENTOR 4 <u>J.Y. Wu</u> |
| DATE <u>7/7/1997</u> | DATE <u>6/25/97</u> |
| SIGNATURE OF INVENTOR 5 <u>Water Lur</u> | SIGNATURE OF INVENTOR 6 <u>Shih-Wei Sun</u> |
| DATE <u>Jun. 26, 1997</u> | DATE <u>6/25/97</u> |

| | | |
|--|----------------------|--|
| REVOCATION OF POWER OF ATTORNEY OR AUTHORIZATION OF AGENT | Application Number | 09/546,174 |
| | Filing Date | April 11, 2000 |
| | First Named Inventor | Chih-Chien Liu, Ta-Shan Tseng, W. B. Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun |
| | Group Art Unit | 1746 |
| | Examiner Name | |
| | Attorney Docket No. | JIA-462C1 |

I hereby revoke all previous powers of attorney or authorizations of agent given in the above-identified application:

☐ A Power of Attorney or Authorization of Agent is submitted herewith.

OR

☒ The undersigned hereby appoints the following attorneys to prosecute and transact all business in the U.S. Patent & Trademark Office in connection with the above-referenced application or patent, with all correspondence directed to said attorney at the address provided:

☒ Customer Number

25235

Type Customer Number here



Firm or Individual Name

Address

Address

City

State

ZIP

Country

Telephone

Fax

I am the:



Applicant.



Assignee of record of the entire interest.

A Certificate under 37 CFR 3.73(b) is enclosed.

SIGNATURE of Assignee of Record

Typed or Printed Name

Larry Lin, United Microelectronics Corp.

Signature

Larry Lin

Date

09/11/00 12:00

ASSIGNMENT

Attorney Docket No. UMC-96-279

| | | |
|--|--------------------|------------------|
| (1-8) Insert Name(s) of Inventor(s) | (1) Chih-Chien Liu | (5) Water Lur |
| | (2) Ta-Shan Tseng | (6) Shih-Wei Sun |
| | (3) W.B. Shieh | (7) |
| | (4) J.Y. Wu | (8) |

In consideration of the sum of one dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

| | |
|--|---|
| (9) Insert name of Assignee | (9) UNITED MICROELECTRONICS CORPORATION |
| (10) Insert state of incorporation of Assignee | (10) TAIWAN, R.O.C. |
| (11) Insert address of Assignee | (11) of No. 13 Innovation First Road, Science Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C. (hereinafter designated as the Assignee), its successors and assigns, the entire and exclusive worldwide right, title and interest in, any Letters Patent which may be granted and issued for, any continuations, divisions, reissues and extensions of said Letters Patent and all international priority rights associated with the invention known as |
| (12) Insert identification of invention, such as Title, Case Number or Foreign App. Number | (12) High Density Plasma Chemical Vapor Deposition Process for which the undersigned has (have) executed an application for patent in the United States of America |
| (13) Insert Date of Signing of Declaration | (13) on 6/24/97, 6/25/97, 7/7/97 |

- (1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.
- (2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.
- (3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.
- (4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.
- (5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

ASSIGNMENT -- Page 2.

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- (6) The undersigned hereby grant WILLIAM H. WRIGHT, Reg. No. 36,312, J. NICHOLAS GROSS, Reg. No. 34,175 and ALAN S. RAYNES, Reg. No. 39,809; the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent & Trademark Office for recordation of this document.

| | | | |
|--------------------|----------------------------------|-----------------|--------|
| Date: 5/24/97 | Name of Inventor: Chih-Chien Liu | Liu, Chih-Chien | (SEAL) |
| Date: 6/24/97 | Name of Inventor: Ta-Shan Tseng | Ta-Shan Tseng | (SEAL) |
| Date: 7/7/1997 | Name of Inventor: W.B. Shieh | W.B. Shieh | (SEAL) |
| Date: 6/25/97 | Name of Inventor: J.Y. Wu | J.Y. Wu | (SEAL) |
| Date: Jun 26, 1997 | Name of Inventor: Water Lur | Water Lur | (SEAL) |
| Date: 6/25/97 | Name of Inventor: Shih-Wei Sun | Shih-Wei Sun | (SEAL) |
| Date: | Name of Inventor: | | (SEAL) |
| Date: | Name of Inventor: | | (SEAL) |